

What is claimed is:

1. A manufacturing method of a multilayer substrate comprising a plurality of wiring layers having wiring and/or electrodes and laminated via an insulating material, comprising:

providing a positioning section in a first wiring layer;

patterning a second wiring layer and/or any subsequent wiring layers using the positioning section in the first wiring layer as a reference.

2. A manufacturing method of a multilayer substrate comprising a plurality of wiring layers having wiring and/or electrodes formed on both surfaces of a core section comprising an insulating material and insulated thereby, comprising:

providing an positioning section in a first wiring layer formed on at least a surface of the core section;

patterning a second wiring layer and/or any subsequent wiring layers using the positioning section in the first wiring layer as a reference.

3. A manufacturing method of a multilayer substrate comprising a plurality of wiring layers having wiring and/or electrodes formed on both surfaces of a core section comprising a sheet-like insulating material and insulated thereby, comprising:

providing a positioning section penetrating the core section perpendicularly and including a part of a first wiring layer formed on both surfaces of the core section;

patterning a second wiring layer and/or any subsequent wiring layers using the positioning section in the first wiring layer as a reference.

4. The method according to any of the claims from 1 to 3, wherein when the positioning section is used as a reference, the insulating material and the wiring layer formed on the positioning section are removed.

5. The method according to any of the claims from 1 to 3, wherein the positioning section is circular.

6. The method according to any of the claims from 1 to 3, wherein a position of the wiring layer used as a reference is identified by using X-rays.

7. A manufacturing method of a multilayer substrate, comprising:

preparing a sheet having a first conductive film laminated on both surfaces of a first

insulating film used as a core;

forming a circular positioning hole penetrating the sheet;

etching both first conductive films corresponding to a first connecting section using the positioning hole as a reference and removing the exposed first insulating film to provide a first through-hole;

forming a conductive film on both first conductive films and in the first through-hole;

patterning both conductive films by using the positioning hole as a reference to form a first wiring layer;

forming a second conductive film on both surfaces of the sheet via a second insulating film;

exposing the positioning hole, etching the second conductive film corresponding to a second connecting section and removing the exposed second insulating film to form a second through-hole;

forming a conductive film on both surfaces of the second conductive film and in the second through-hole, and

patterning the second conductive film using the positioning hole as a reference to form a second wiring layer.

8. The method according to claim 7, wherein the positioning hole positioned under the second conductive film are identified by X-rays.

9. The method according to claim 7, wherein the first wiring layer forming the positioning hole is provided in a sword guard-shape at a periphery of an opening and laser is irradiated on inner walls of the first wiring layer to remove the second insulating film.